

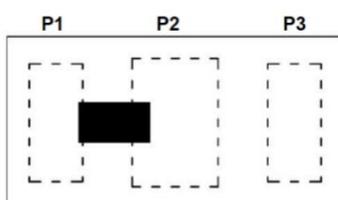
### Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

### Specifications

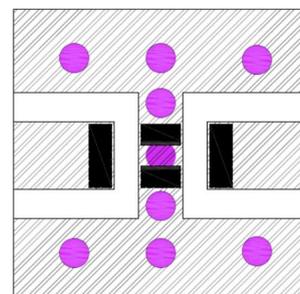
NO.	Parameter	SPC	
1	Frequency range	2300~2600 MHz	
2	Insertion Loss	2300.00 – 2320.00 MHz	1.10 dB max. at 25 °C 1.15 dB max. at -40 ~ +85 °C
		2320.00 – 2370.00 MHz	0.93 dB max. at 25 °C 0.98 dB max. at -40 ~ +85 °C
		2370.00 – 2390.00 MHz	0.69 dB max. at 25 °C 0.74 dB max. at -40 ~ +85 °C
		2496.00 – 2690.00 MHz	0.52 dB max. at 25 °C 0.57 dB max. at -40 ~ +85 °C
		2555.00 – 2575.00 MHz	0.46 dB max. at 25 °C 0.51 dB max. at -40 ~ +85 °C
		2575.00 – 2635.00 MHz	0.45 dB max. at 25 °C 0.50 dB max. at -40 ~ +85 °C
		2635.00 – 2655.00 MHz	0.42 dB max. at 25 °C 0.47 dB max. at -40 ~ +85 °C
3	Attenuation	1710.00 – 1785.00 MHz	24.0 dB min.
		1805.00 – 1880.00 MHz	23.0 dB min.
		1880.00 – 1920.00 MHz	23.0 dB min.
		1850.00 – 1915.00 MHz	23.0 dB min.
		1920.00 – 1980.00 MHz	24.0 dB min.
4	Return Loss in BW (dB)	2300.00 – 2690.00 MHz	13.0 dB max.
5	Port Impedance		50Ω
6	Power		3W max.
7	Operation Temperature Range	-40°C ~ +85°C	

### Construction



PIN	Connection
P1	Input port
P2	GND
P3	Output port

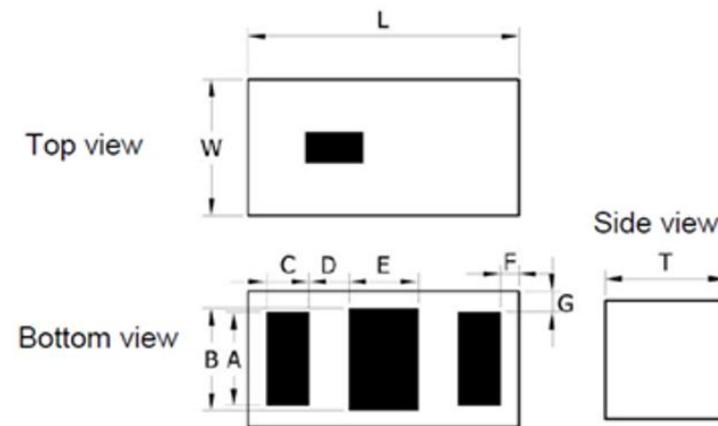
### Mounting Considerations



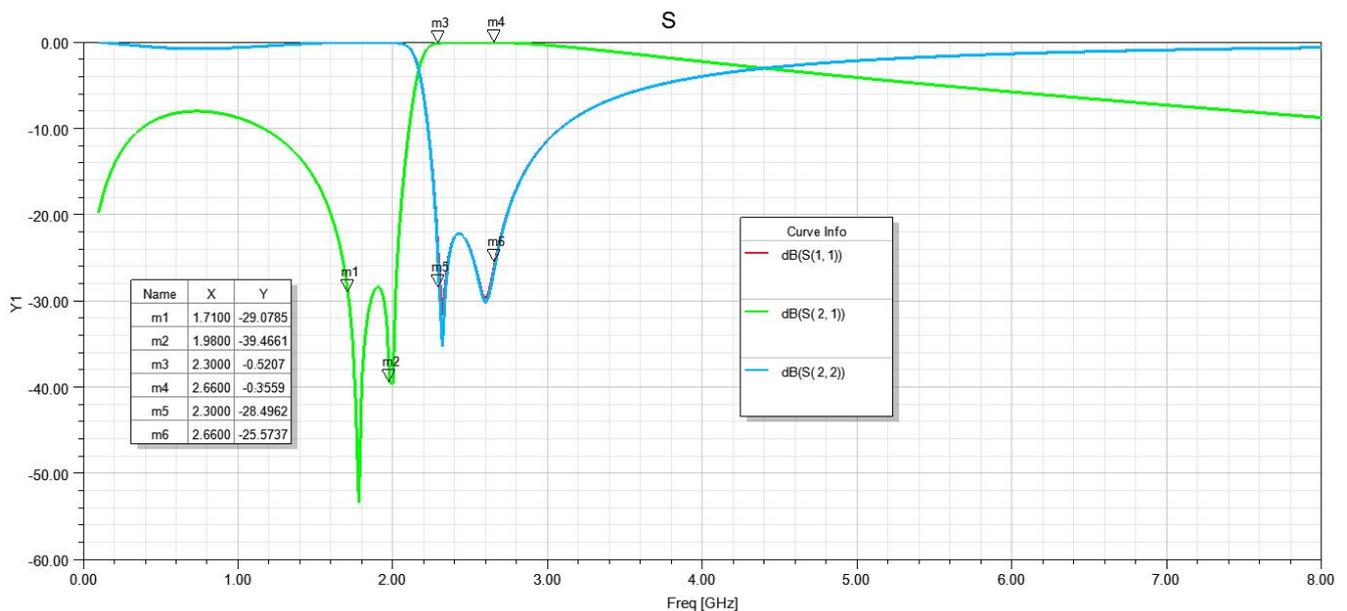
Unit: mm

Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

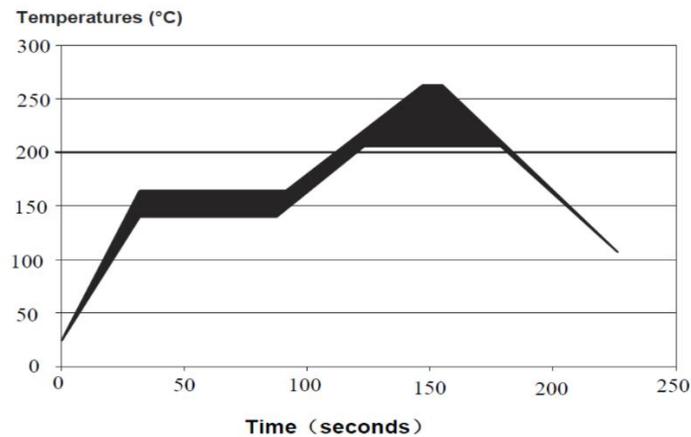
### Dimensions

Figure	Symbol	Dimension (mm)
	L	1.6 ± 0.10
	W	0.8 ± 0.10
	T	0.65 max.
	A	0.55 ± 0.10
	B	0.60 ± 0.10
	C	0.25 ± 0.10
	D	0.23 ± 0.05
	E	0.40 ± 0.10
	F	0.12 ± 0.05
G	0.125 ± 0.05	

### Typical Electrical Characteristics (T=25°C)



### Solder Reflow Standard Conditioning



### Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) \*

Baking : Unnecessary

\* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.